

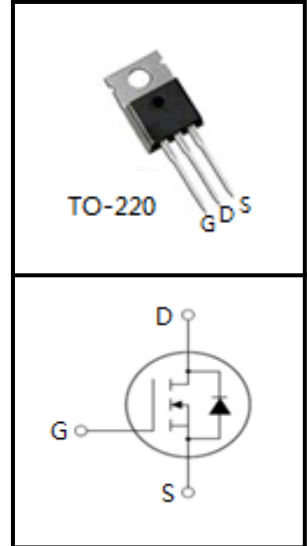
68V N-Channel Trench MOSFET

FEATURES

- Trench Power MOSFET Technology
- Low $R_{DS(ON)}$
- Low Gate Charge
- Optimized For Fast-switching Applications

APPLICATIONS

- DC/DC Converters
- Synchronous Rectification



Device Marking and Package Information

Device	Package	Marking
CTP06N6P8	TO-220	CTP06N6P8

Absolute Maximum Ratings at $T_j = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0V$)	V_{DSS}	68	V
Continuous Drain Current $T_C = 25^\circ\text{C}$ (note2)	I_D	115	A
Continuous Drain Current $T_C = 100^\circ\text{C}$ (note2)		85	A
Pulsed Drain Current (note1)	I_{DM}	460	A
Gate Source Voltage	V_{GSS}	± 20	V
Single Pulse Avalanche Energy (note1)	E_{AS}	487	mJ
Avalanche Current	I_{AS}	57	A
Power Dissipation $T_C = 25^\circ\text{C}$ (note3)	P_D	158	W
Power Dissipation $T_C = 100^\circ\text{C}$ (note3)		79	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+175	$^\circ\text{C}$

Thermal Characteristics

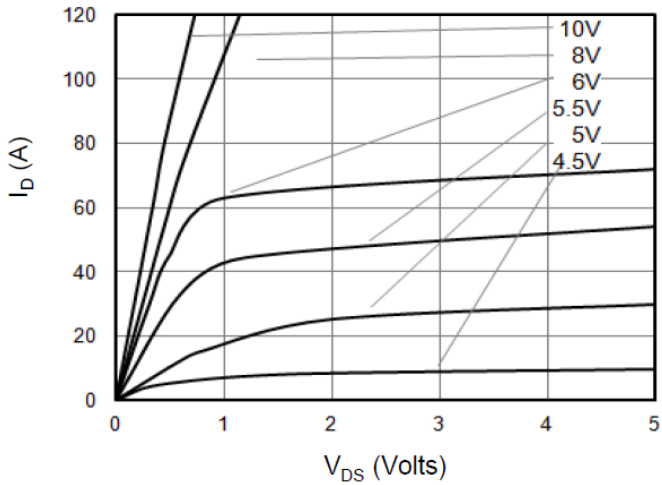
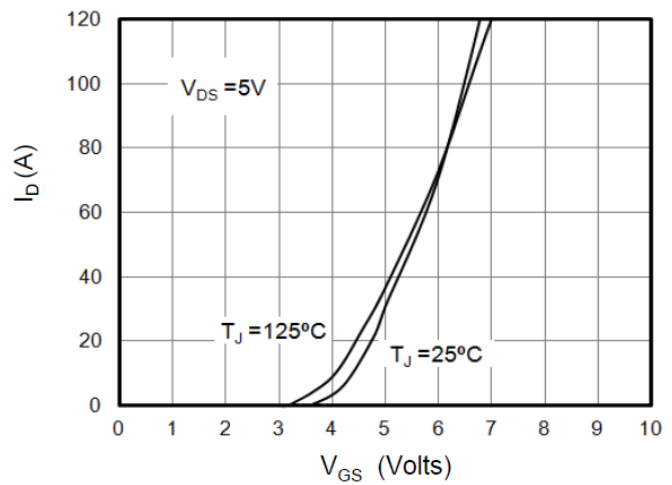
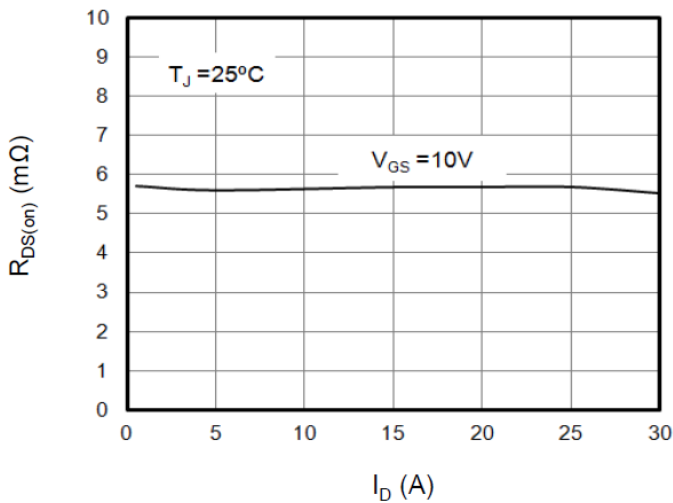
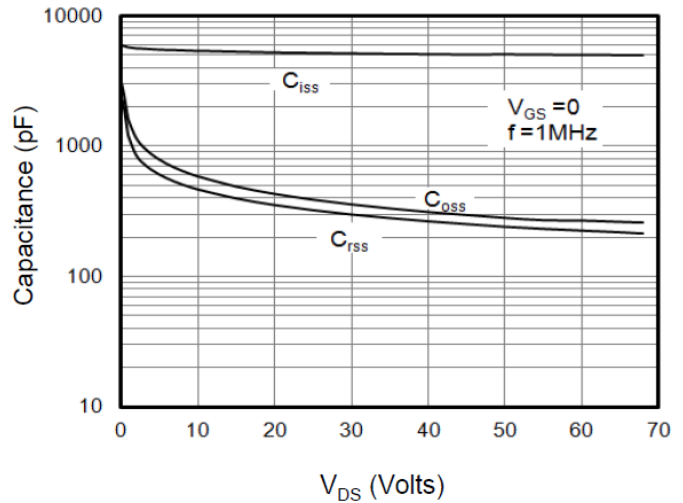
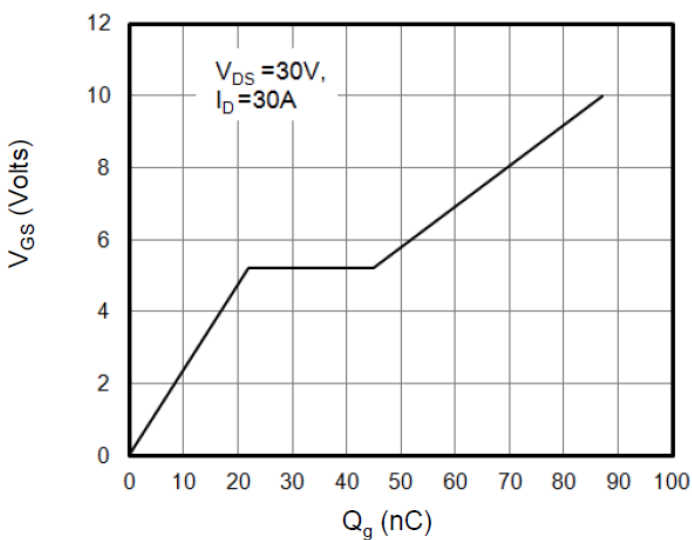
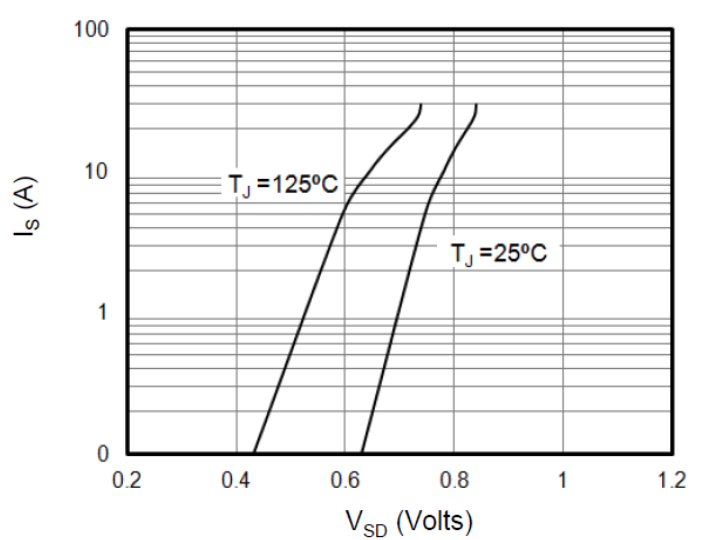
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	0.95	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	64	

Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	68	--	--	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 68V, V_{GS} = 0V, T_J = 25^\circ\text{C}$	--	--	1	μA
		$V_{DS} = 68V, V_{GS} = 0V, T_J = 100^\circ\text{C}$	--	--	25	μA
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20V$	--	--	± 100	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	V
Drain-Source On-Resistance (note2)	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	--	5.4	6.8	m Ω
Forward Transconductance	gfs	$V_{DS} = 5V, I_D = 20A$	--	30	--	S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0V,$ $V_{DS} = 30V,$ $f = 1.0\text{MHz}$	--	5094	--	pF
Output Capacitance	C_{oss}		--	332	--	
Reverse Transfer Capacitance	C_{riss}		--	282	--	
Total Gate Charge	Q_g	$V_{DS} = 30V, I_D = 30A,$ $V_{GS} = 10V$	--	87	--	nC
Gate-Source Charge	Q_{gs}		--	23	--	
Gate-Drain Charge	Q_{gd}		--	22	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DD} = 30V, I_D = 30A,$ $R_G = 2.5\Omega, V_{GS} = 10V$	--	23	--	ns
Turn-on Rise Time	t_r		--	18	--	
Turn-off Delay Time	$t_{d(off)}$		--	67	--	
Turn-off Fall Time	t_f		--	30	--	
Body Diode Characteristics						
Source-Drain Current(Body Diode)	I_{SD}	$T_C = 25^\circ\text{C}$	--	--	115	A
Pulsed Source-Drain Current(Body Diode)	I_{SDM}		--	--	460	
Body Diode Voltage	V_{SD}	$T_J = 25^\circ\text{C}, I_{SD} = 30A, V_{GS} = 0V$	--	--	1	V
Reverse Recovery Time	t_{rr}	$I_F = 30A$ $di_F/dt = 100A/\mu s$	--	33	--	ns
Reverse Recovery Charge	Q_{rr}		--	122	--	nC

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{AS} = 30A, V_{DD} = 50V, L = 0.3\text{mH}, R_G = 25\Omega, \text{Starting } T_J = 25^\circ\text{C}$
3. The power dissipation PD is based on $T_J(\text{MAX}) = 175^\circ\text{C}$, using junction-to-case thermal resistance.

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1: On-Region Characteristics

Figure 2: Transfer Characteristics

Figure 3: On-Resistance vs. Drain Current

Figure 4: Capacitance Characteristics

Figure 5: Gate Charge Characteristics

Figure 6: Body Diode Forward Voltage

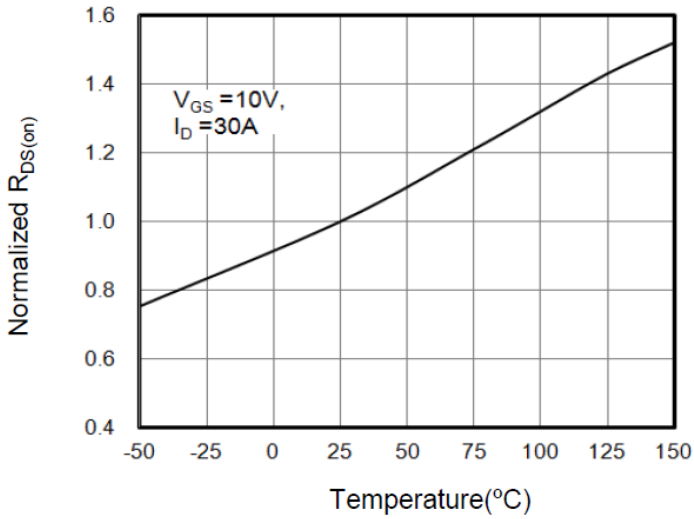
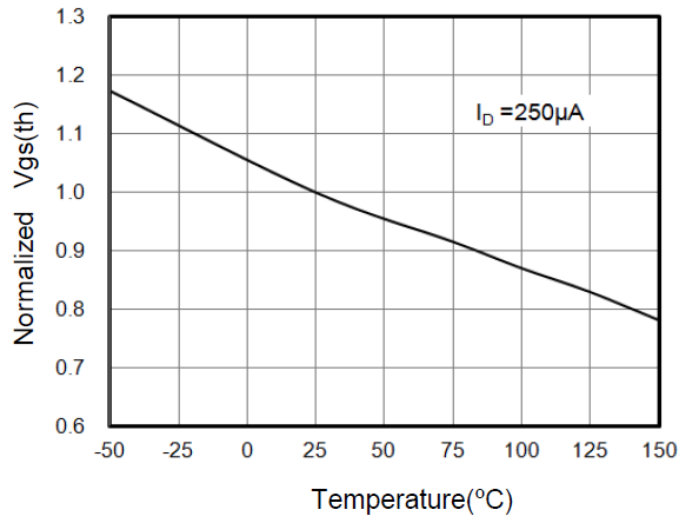
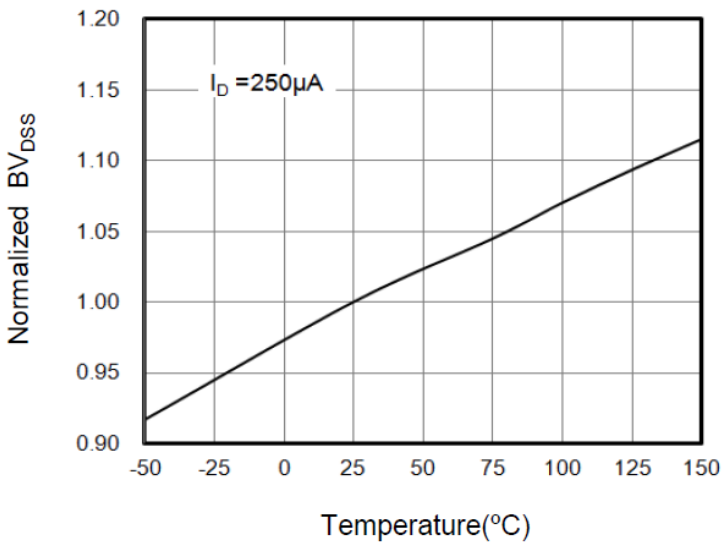
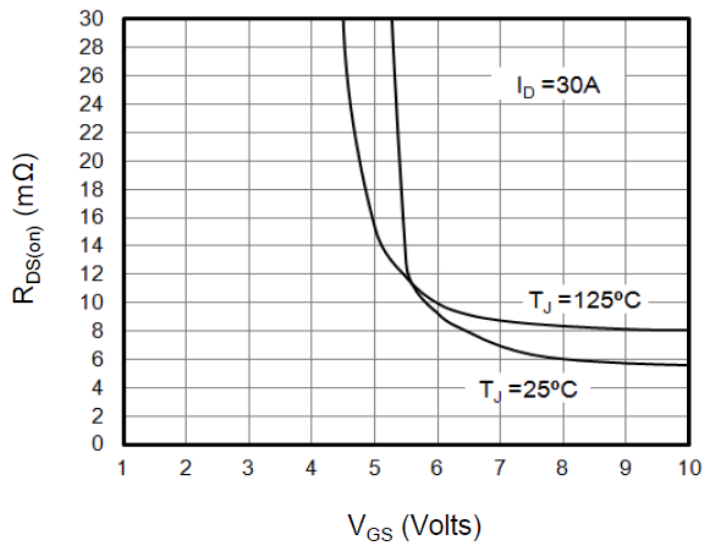
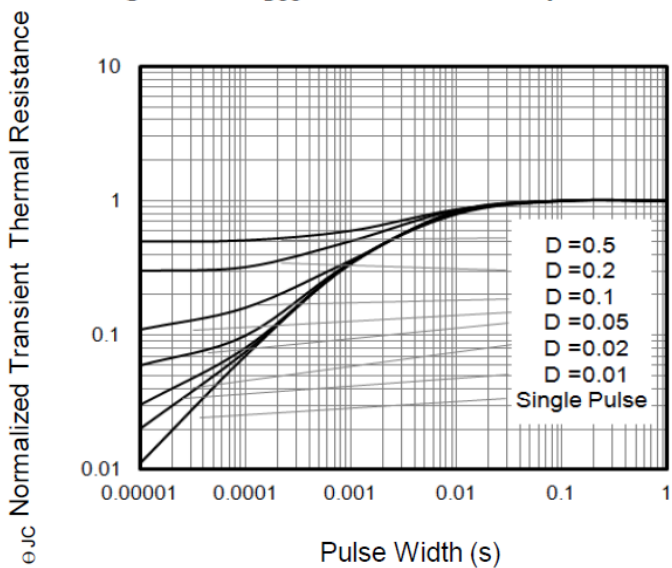
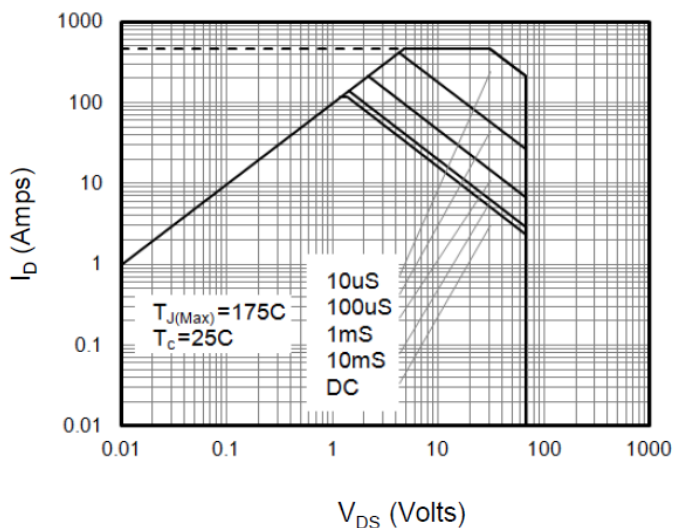
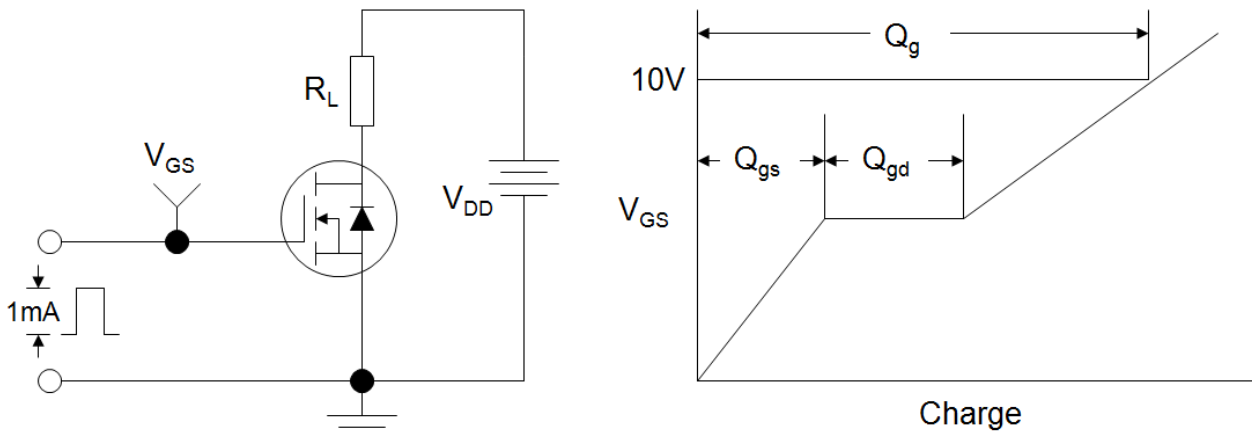
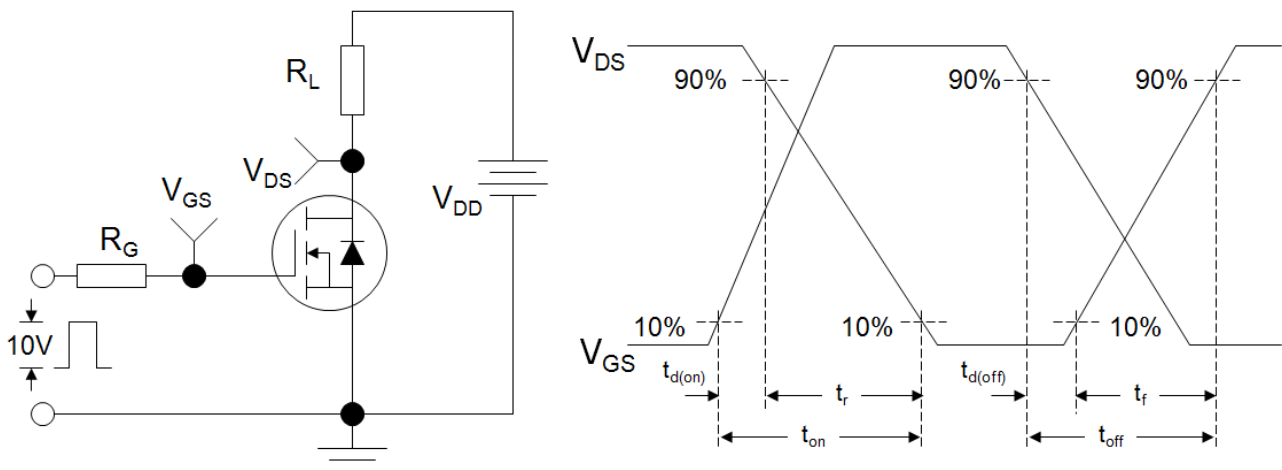
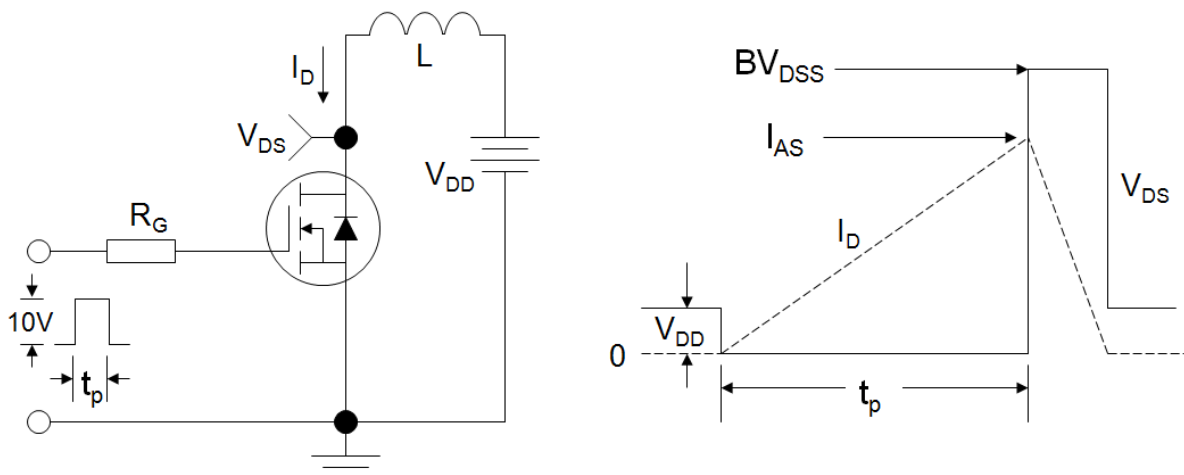
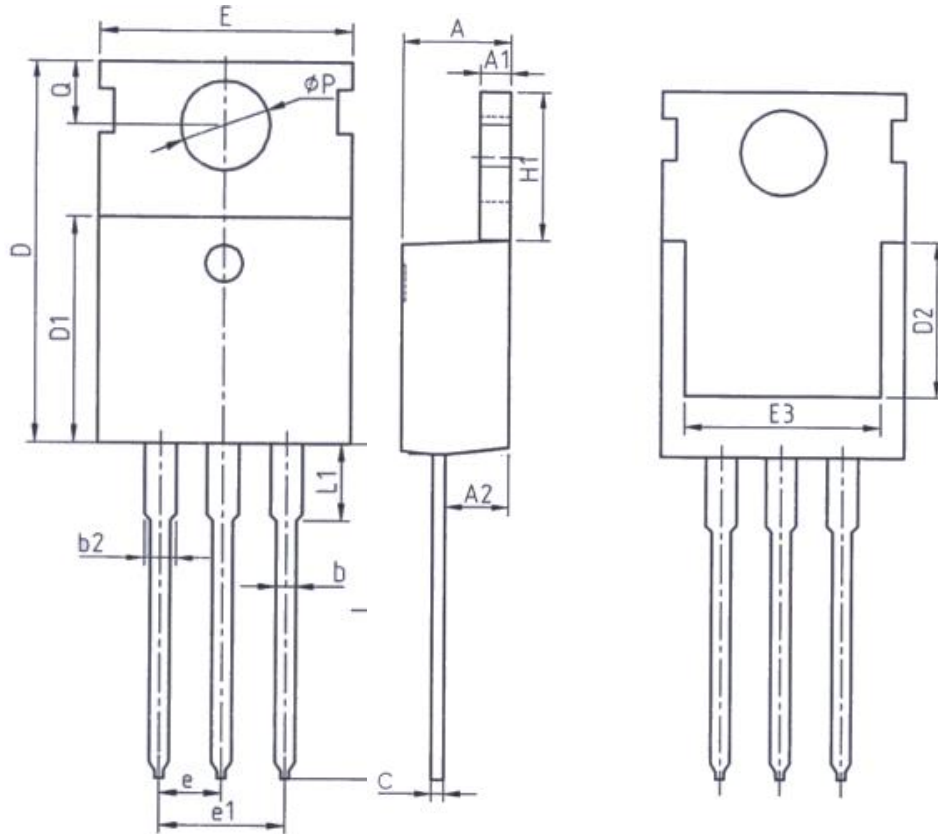
Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7: On-Resistance vs. Junction Temperature

Figure 8: $V_{GS(th)}$ vs. Junction Temperature

Figure 9: $BV_{DS(s)}$ vs. Junction Temperature

Figure 10: On-Resistance vs. Gate-Source Voltage

Figure 11: Normalized Transient Thermal Resistance

Figure 12: Safe Operating Area

Figure A: Gate Charge Test Circuit and Waveform

Figure B: Resistive Switching Test Circuit and Waveform

Figure C: Unclamped Inductive Switching Test Circuit and Waveform


TO-220


Unit: mm		
Symbol	Min.	Max.
A	4.37	4.77
A1	1.25	1.45
A2	2.20	2.60
b	0.70	0.95
b2	1.17	1.47
c	0.40	0.65
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-

Unit: mm		
Symbol	Min.	Max.
E	9.70	10.30
E3	7.00	-
e	2.54BSC	
e1	5.08BSC	
H1	6.25	6.85
L	12.75	13.80
L1	-	3.40
P	3.40	3.80
Q	2.60	3.00

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